

LX10M

● FEATURES

- * Halogen-free type
- * Glass passivated chip junctions
- * Compliance to RoHS product
- * Leadless chip form, no lead damage
- * Low power loss, High efficiency
- * High current capability
- * Plastic package has Underwriters Laboratory Flammability Classification 94V-0

● APPLICATION

- * Lighting
- * AC/DC Power Supply
- * Communication Equipment

● MECHANICAL DATA

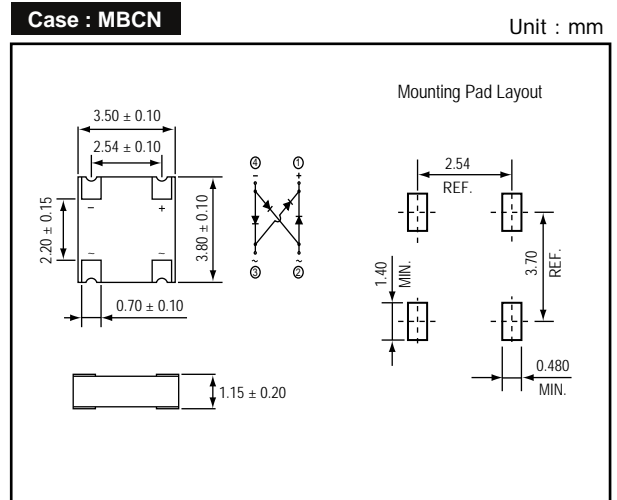
Case : Packed with FRP substrate and epoxy underfilled

Terminals : Pure Tin plated (Lead-Free),
solderable per MIL-STD-750, Method 2026.

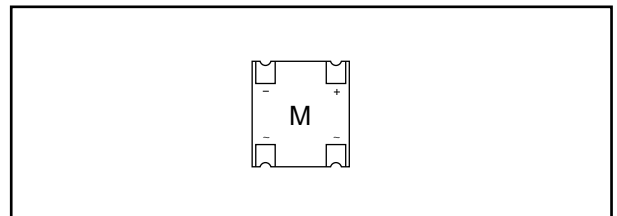
● PACKING

- * 5,000 pieces per 13" (330mm ± 2mm) reel
- * 2 reels per box
- * 5 boxes per carton

● OUTLINE DIMENSIONS



● MARKING



Absolute Maximum Ratings (Ta = 25 °C)

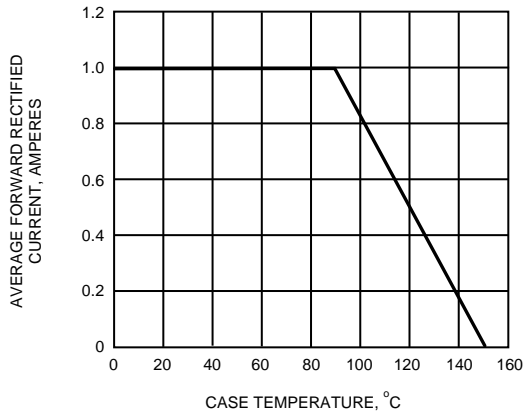
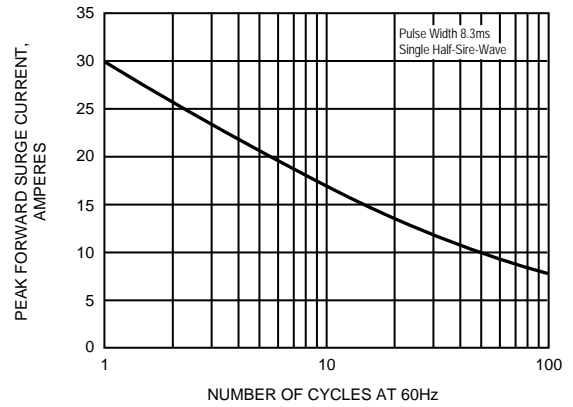
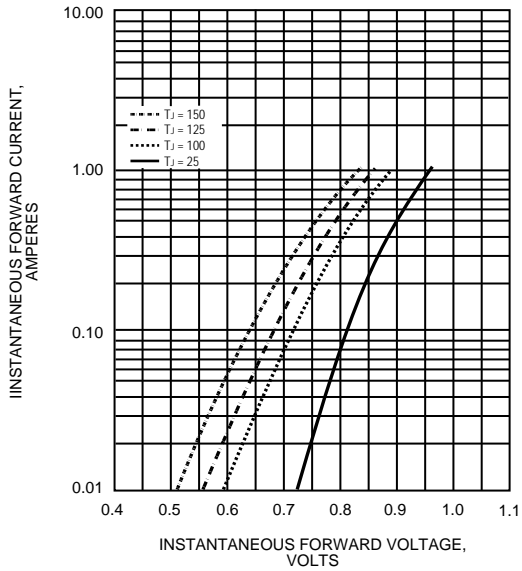
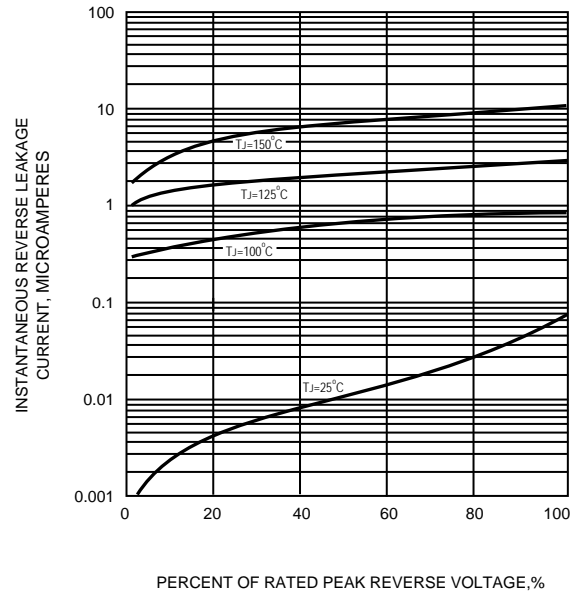
ITEM	Symbol	Conditions	Rating	Unit
Repetitive peak reverse voltage	VRRM		1000	V
Average forward current	IF(AV)		1.0	A
Peak forward surge current	IFSM	8.3ms single half sine-wave	30	A
Operating junction and storage temperature Range	Tj,TSTG		-55 to +150	°C

Electrical characteristics (Ta = 25 °C)

ITEM	Symbol	Conditions	Min.	Typ.	Max.	Unit
Forward voltage	VF	@IF = 0.4A	-	0.90	1.0	V
		@IF = 1.0A	-	-	1.1	
Repetitive peak reverse current	IRRM	VR = Max. VRRM	-	0.08	5	uA
			-	-	100	
Current squared time	I ² t	t < 8.3ms, Ta = 25 °C	-	3.74	-	A ² s
Junction capacitance	Cj	VR = 4V, f = 1.0 MHz	-	9	-	pF
Typical thermal resistance per leg	Rth(JA)	Junction to ambient (Note 1)	-	130	-	°C/W
	Rth(JC)	Junction to case (Note 1)	-	40	-	°C/W

NOTES: (1) On glass epoxy P.C.B. mounted on 0.05" x 0.05" (1.3 x 1.3 mm) solder pads.

(2) Apply the product under 10 Watts

FIG.1 - FORWARD CURRENT DERATING CURVE

FIG.2 - MAXIMUM NON-REPETITIVE PEAK FORWARD SURGE CURRENT

FIG.3 - TYPICAL INSTANTANEOUS FORWARD CHARACTERISTICS

FIG.4 - TYPICAL REVERSE CHARACTERISTICS

FIG.5 - TYPICAL JUNCTION CAPACITANCE
